

The Stackup Legend below this is static.
If you change the stackup, update the Legend.

Layer Name	Gerber Document	Copper Thickness	Dielectric Material
Top Solder Mask	(.GTS)		Solder Resist
Top Layer	(.GTL)	1.4mil	
Bottom Layer	(.GBL)	1.4mil	FR-4
Bottom Solder Mask	(.GBS)		Solder Resist

This document can handle board shapes up to 7.9in x 10in, although our panel vendors top out at 7in x 10in.

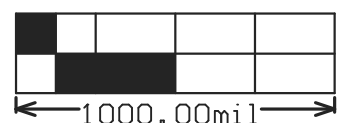
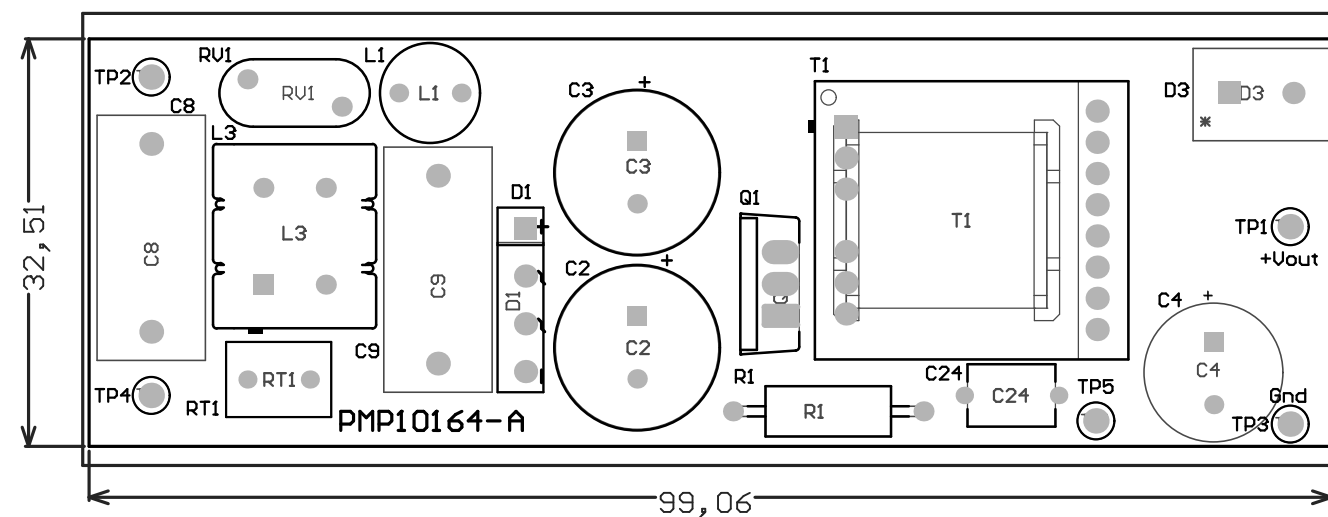
To re-size the board shape, do the following:

- Select lines on M1 Board Outline and delete (easy in single layer mode...shift+s)
- Draw a rectangle using lines (example will be for a 4 x 6 board
 - Enter Place Line mode (keyboard pl)
 - keyboard jo to jump to origin, hit enter
 - keyboard jl to jump to location, set x to 6000, hit enter twice
 - keyboard jl to jump to location, set x to 6000 and y to 4000, hit enter twice
 - keyboard jl to jump to location, set x to 0 and y to 4000, hit enter twice
 - keyboard jo to jump to origin, hit enter
 - Hit ESC twice to exit place line mode
- Select lines on M1 Board Outline
- Menu Design|Board Shape|Define from Selected Objects (keyboard dsd)

To define a Keep-Out that mirrors the board outline:

- Menu Design|Board Shape|Create Primitives From Board Shape (keyboard dsp)
 - Set the Keep-Out Layer as the layer, set width as preferred
 - Ensure Route Tool Outline is selected, hit enter

If you re-size the board, don't forget to move the drill table strings on the Drill Drawing Layer...they should be just to the right of your board shape



COMPONENTS MARKED 'DNP' SHOULD NOT BE ORDERED TO THE CUSTOMER. TO ORDER, REMOVE 'DNP' FROM THE PART NUMBER.
ASSEMBLY VARIANT: [No Variations] [Variations: 0]

[illegible]

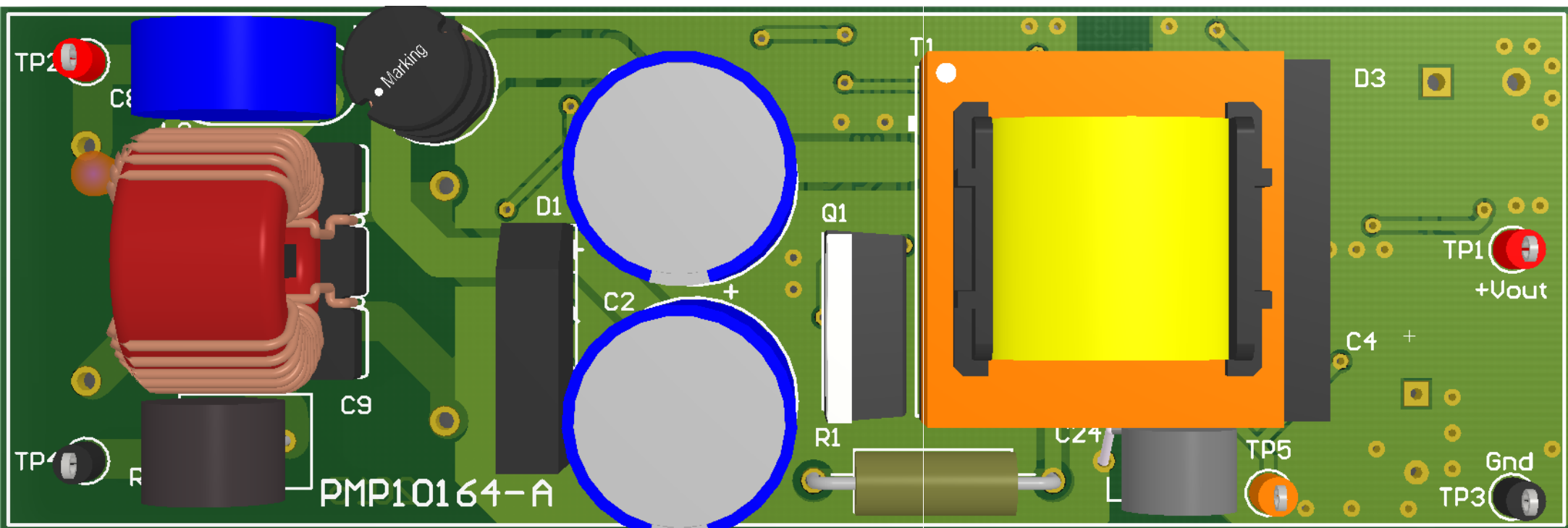
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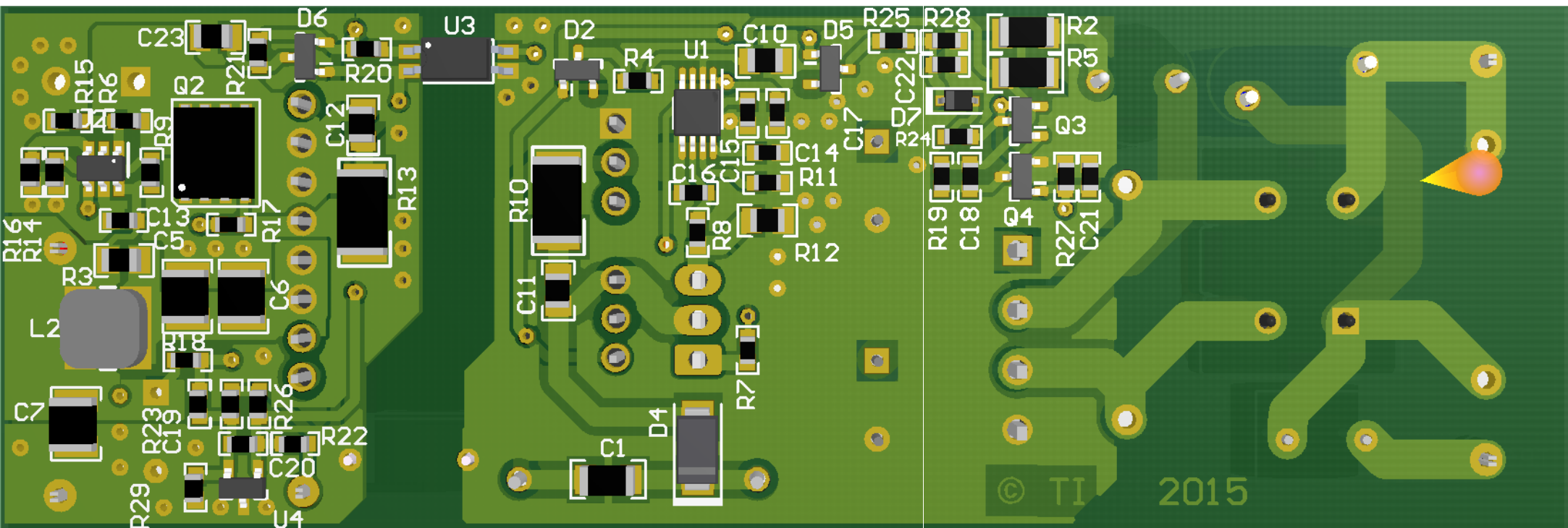
DESIGN INFORMATION	
MIN. TRACK WIDTH:	8 MIL
MIN. CLEARANCE:	0.2 mm
MIN. VIA PAD SIZE:	24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL PER IPC-D-275 CLASS 2 LEVEL C	
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL	
MATERIAL:	
☐ FR-408	☒ FR-4 High Tg ☐ OTHER _____
THICKNESS:	☒ 62 MIL (1.6mm) +/-10% ☐ OTHER _____
TOLERANCE:	☒ ANSI IPC-6012 TYPE 3 CLASS 2 ☐ OTHER +/- _____
BOW & TWIST:	☒ ANSI IPC-6012 TYPE 3 CLASS 2 ☐ OTHER +/- _____
DRILLING:	
REFERENCE:	☒ AS SHOWN ☒ NC_DRILL FILES
PTH MIN COPPER THICKNESS:	☒ 1MIL ☐ OTHER _____
BOARD FINISH:	
SILKSCREEN:	☒ TOP ☒ BOTTOM
SILKSCREEN COLOR:	☒ WHITE ☐ OTHER _____
SOLDER RESIST COLOR:	
☒ GREEN ☐ BLUE ☐ OTHER _____	
SURFACE FINISH:	
☒ IMMERSION GOLD (ENIG) ☐ ENEPIG ☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER _____	
ARRAY/PANEL:	
☐ CUT AND TRIM PER MECH LAYER 1 ☐ N.C. ROUTE ☒ V. SCORE	
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCB'S TO MEET OR EXCEED THE REQUIREMENTS OF:	
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3	
☒ UL 94V-0 ☒ RoHS ☐ OTHER _____ PER ORDER	
ADDITIONAL REQUIREMENTS:	
MICROSECTION: ☐ YES	
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER	
MANUFACTURER'S UL: ☐ RAIL ☐ METAL ☒ SILK	


TEXAS INSTRUMENTS

PROJECT TITLE: Universal input to 10.5V@1.8A Sync Flyback
DESIGNED FOR: Public Release
FILE NAME: PMP10164 Rev_B PCB.PcbDoc

ENGINEER: R. Scibilia	LAYOUT BY: Who did the Layout?
SCALE: 1.00	ALTUM DESIGNER VERSION: 10.0.0.27009





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